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电性参数

Power Dissipation	Pd	125	mw
(Continuous Forward Current)	IF	50	mA
Pulsed Forward Current (1/10Duty Cycle, 0.1msPulsewidth)	IFP	200	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	
Storage Temperature	Tstg	-40 ~ +85	
(Junction Temperature)	Tj	≤115	

光电参数 Ta=25















使用注意事项 (1)

Precautions (1)

贮存:



Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

30 °C or less 60%RH

Before opening the package, the product should be kept at 30 °C or less and humidity less than 60% RH, and be used within a year.

30 °C or less 10%RH 168 hours (7 days)

30 °C or less 60%RH

After opening the package, the product should be stored at 30 °C or less and humidity less than 10%RH, and be soldered within 168 hours (7 days). It is recommended that the product be operated at the workshop condition of 30 °C or less and humidity less than 60%RH.

LED
DH001A

60 °C 5 minutes

If the moisture absorbent material is used, the product should be stored at 30 °C or less and humidity less than 10%RH, and be soldered within 168 hours (7 days). It is recommended that the product be operated at the workshop condition of 30 °C or less and humidity less than 60%RH.

使用注意事项（2）

Precautions (2)



LE



A

LED



In designing a circuit, the current should be controlled for each LED. In the meantime, the current will cause big current change, and the current will be too large. It is recommended to use a constant current source.



When handling, touching the encapsulant will not only contaminate its surface, but also affect the performance of the encapsulant.

